

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
 Stylesheet Version v1.2

EPAS ID: PAT3148532

SUBMISSION TYPE:	NEW ASSIGNMENT	
NATURE OF CONVEYANCE:	ASSIGNMENT	
CONVEYING PARTY DATA		
	Name	Execution Date
	CHENGJIE ZUO	11/05/2014
	CHANGHAN YUN	11/05/2014
	SANG-JUNE PARK	11/25/2014
	CHI SHUN LO	11/11/2014
	MARIO F. VELEZ	11/26/2014
	JONGHAE KIM	11/05/2014
RECEIVING PARTY DATA		
Name:	QUALCOMM Incorporated	
Street Address:	5775 Morehouse Drive	
Internal Address:	Patent Department	
City:	San Diego	
State/Country:	CALIFORNIA	
Postal Code:	92121-1714	
PROPERTY NUMBERS Total: 1		
	Property Type	Number
	Application Number:	13356717
CORRESPONDENCE DATA		
Fax Number:	(858)658-2502	
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>		
Phone:	858-658-4351	
Email:	us-docketing@qualcomm.com	
Correspondent Name:	QUALCOMM INCORPORATED	
Address Line 1:	5775 MOREHOUSE DRIVE	
Address Line 2:	PATENT DEPARTMENT	
Address Line 4:	SAN DIEGO, CALIFORNIA 92121-1714	
ATTORNEY DOCKET NUMBER:	110996	
NAME OF SUBMITTER:	SAM TALPALATSKY	
SIGNATURE:	/Sam Talpalatsky/	
DATE SIGNED:	12/16/2014	

PATENT

Total Attachments: 6

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ASSIGNMENT

WHEREAS, WE,

1. **Chengjie Zuo**, a citizen of China, having a mailing address located at 5775 Morehouse Drive, San Diego, California 92121 and a resident of San Diego, California,
2. **Changhan Yun**, a citizen of Korea, having a mailing address located at 5775 Morehouse Drive, San Diego, California 92121 and a resident of San Diego, California,
3. **Sang-June Park**, a citizen of Korea, having a mailing address located at 5775 Morehouse Drive, San Diego, California 92121 and a resident of San Diego, California,
4. **Chi Shun Lo**, a citizen of United Kingdom, having a mailing address located at 5775 Morehouse Drive, San Diego, California 92121 and a resident of San Diego, California,
5. **Mario F. Velez**, a citizen of United States of America, having a mailing address located at 5775 Morehouse Drive, San Diego, California 92121 and a resident of San Diego, California,
6. **Jonghae Kim**, a citizen of Korea, having a mailing address located at 5775 Morehouse Drive, San Diego, California 92121 and a resident of San Diego, California,

have conceived of one or more processes, methods, machines, articles of manufacture, designs, compositions of matter, inventions, discoveries or new or useful improvements relating to **STACKED CMOS CHIPSET HAVING AN INSULATING LAYER AND A SECONDARY LAYER AND METHOD OF FORMING SAME** (collectively the "INVENTIONS") for which WE have executed and/or may execute one or more patent applications therefor; and

WHEREAS, QUALCOMM Incorporated (hereinafter "ASSIGNEE"), a Delaware corporation, having a place of business at 5775 Morehouse Drive, San Diego, California 92121-1714, U.S.A., desires to acquire or otherwise obtain the entire right, title, and interest in and to said INVENTIONS, including all inventions related thereto or thereof, all patent applications therefor, and all patents that have granted or may be granted hereafter thereon, including but not limited to those identified below.

NOW, THEREFORE, for good and valuable consideration, the receipt of which is hereby acknowledged, WE do hereby acknowledge that WE have sold, assigned, conveyed, and transferred, and by these presents do hereby sell, assign, convey, and transfer, unto ASSIGNEE, its successors, its legal representatives, and its assigns, the entire right, title, and interest throughout the world in and to said INVENTIONS, including all patent applications therefor that may have been filed or may be filed hereafter for said INVENTIONS in the United States, including but not limited to U.S. Application No(s). 13/356,717 filed January 24, 2012, Qualcomm Reference No. 110996, and all provisional applications relating thereto, together with U.S. Provisional Application No(s). 61/560,471, filed November 16, 2011, Qualcomm

Reference No. 110996P1, (and do hereby authorize ASSIGNEE and its representative to hereafter add herein such application number(s) and/or filing date(s) when known), and all divisional applications, renewal applications, continuation applications, continuation-in-part applications, and design applications thereof, and all issued patents of the United States which may have granted or may be granted hereafter thereon and all reissues, renewals, reexaminations, and extensions to any of the foregoing and all patents issuing thereon in the United States;

AND WE further do acknowledge and agree that WE have sold, assigned, conveyed, and transferred, and by these presents do hereby sell, assign, convey, and transfer, unto ASSIGNEE, its successors, its legal representatives, and its assigns, all rights of priority under International Conventions, Treaties, or Agreements, and the entire right, title, and interest throughout the world in said INVENTIONS, including all inventions related thereto or thereof, and all patent applications therefor that may have been filed or may be filed hereafter for said INVENTIONS in any foreign country, countries, or treaty/union organizations, and all divisional applications, renewal applications, continuation applications, continuation-in-part applications, patent of addition applications, confirmation applications, validation applications, utility model applications, and design applications thereof, and all issued patents which may have granted or may be granted hereafter for said INVENTIONS in any country or countries foreign to the United States, and all reissues, renewals, reexaminations, and extensions thereof;

AND WE DO HEREBY authorize and request the Commissioner of Patents of the United States, and any Official of any country or countries foreign to the United States, whose duty it is to issue patents on applications or registrations, to issue all patents for said INVENTIONS to said ASSIGNEE, its successors, its legal representatives and its assigns, in accordance with the terms of this instrument;

AND WE DO HEREBY sell, assign, transfer, and convey to said ASSIGNEE, its successors, its legal representatives, and its assigns all claims for damages and all remedies arising out of or relating to any violation(s) of any of the rights assigned hereby that have or may have accrued prior to the date of assignment to said ASSIGNEE, or may accrue hereafter, including, but not limited to the right to sue for, seek, obtain, collect, recover, and retain damages and any ongoing or prospective royalties to which WE may be entitled, or that WE may collect for any infringement or from any settlement or agreement related to any of said patents before or after issuance;

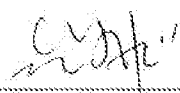
AND WE HEREBY covenant and agree that WE will communicate promptly to said ASSIGNEE, its successors, its legal representatives, and its assigns, any facts known to us respecting said INVENTIONS, and will testify in any legal proceeding, sign all lawful papers, execute all applications and certificates, make all rightful declarations and/or oaths, and provide all lawful assistance to said ASSIGNEE, its successors, its legal representatives and its assigns, to obtain and enforce patent protection for said INVENTIONS in all countries;

AND WE HEREBY represent that WE have full and exclusive, unencumbered right to sell, assign, convey and transfer all subject matter herein, and hereby covenant that WE have not and will not execute any writing or do any act whatsoever conflicting with these presents.

Done at San Diego, on 11/5/14
LOCATION DATE


Chengjie Zuo

Done at San Diego CA, on 11/5/14
LOCATION DATE


Changhan Yun

Done at _____, on _____
LOCATION DATE

Sang-June Park

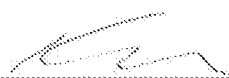
Done at _____, on _____
LOCATION DATE

Chi Shun Lo

Done at _____, on _____
LOCATION DATE

Mario F. Velez

Done at San Diego, on 11-5-2014
LOCATION DATE


Jonghae Kim

Done at _____, on _____
LOCATION DATE

Chengjie Zuo

Done at _____, on _____
LOCATION DATE

Changhan Yun

Done at San Diego, on 11/25/2014
LOCATION DATE


Sang-June Park

Done at _____, on _____
LOCATION DATE

Chi Shun Lo

Done at _____, on _____
LOCATION DATE

Mario F. Velez

Done at _____, on _____
LOCATION DATE

Jonghae Kim

Done at _____, on _____
LOCATION DATE

Chengjie Zuo

Done at _____, on _____
LOCATION DATE

Changhan Yun

Done at _____, on _____
LOCATION DATE

Sang-June Park

Done at Hong Kong, on 11/11/2014
LOCATION DATE

Chi Shun Lo

Done at _____, on _____
LOCATION DATE

Mario F. Velez

Done at _____, on _____
LOCATION DATE

Jonghae Kim

PATENT

QUALCOMM Ref. No. 110996


Page 3 of 3

Done at _____, on _____
LOCATION DATE Chengjie Zuo

Done at _____, on _____
LOCATION DATE Changhan Yun

Done at _____, on _____
LOCATION DATE Sang-June Park

Done at _____, on _____
LOCATION DATE Chi Shun Lo

Done at San Diego, on 11-26-14
LOCATION DATE 
Mario F. Velez

Done at _____, on _____
LOCATION DATE Jonghae Kim

PATENT

RECORDED: 12/16/2014

REEL: 034512 FRAME: 0084